



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20200723001.1

**Transfer of select BiFET devices from GFAB to FFAB Wafer Fab site
Change Notification / Sample Request**

Date: July 28, 2020

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team
SC Business Services

20200723001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
JM38510/11402BGA	null
JM38510/11906BCA	null
LF156 MD8	null
LF156H/883	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20200723001.1	PCN Date:	Jul 28, 2020
Title:	Transfer of select BiFET devices from GFAB to FFAB Wafer Fab site		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Oct 28, 2020	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Assembly Materials	
<input type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input type="checkbox"/> Mechanical Specification	
<input type="checkbox"/> Test Site	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process	
<input checked="" type="checkbox"/> Wafer Fab Site	<input checked="" type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Wafer Fab Process	
	<input type="checkbox"/> Part number change		

PCN Details

Description of Change:

This change notification is to announce the transfer of select BiFET devices from GFAB to the FFAB (FR-BIP-1) Wafer Fab site for the selected devices listed in the "Product Affected" section.

Current Fab Site			New Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
GFAB6	BiFET	150 mm	FFAB	BiFET	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Greenock, Scotland (GFAB) Wafer Fab site closure.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:


Current:

Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
GFAB6	GF6	GBR	Greenock

New Fab Site:

New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL 2 / 260C/1 YEAR	SEAL DT
MSL 1 / 235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

JL156BGA	JM38510/11906BCA	LF156H/883	M38510/11402BGA
JM38510/11402BGA	LF156 MD8	LF444MD/883	

Qualification Report

Approve Date 20-Jul-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LF147J/883	Qual Device: LF412MJ/883	Qual Device: LF156H/883
-	Ax Electrical Test	ClassV, GroupA	1/30/0	1/30/0	1/30/0
-	B2 Bond Strength	22 Wires, Min 4 Units Condition C or D	1/22/0	1/22/0	1/22/0
-	B3 Solderability	245C +/-5%, minimum of 3 devices	1/3/0	1/3/0	1/3/0
-	D2 Lead Integrity	Condition B2, 3 units, 45 leads minimum	1/45/0	1/45/0	1/45/0
-	D3 Sequence	-	1/15/0	1/15/0	1/15/0
-	D4 Sequence	-	1/15/0	1/15/0	1/15/0
CDM	ESD CDM	+/- 250V, 500V*, 750V*, 1000V*, 1500V*	1/3/0	1/3/0	-
ED	Electrical Characterization, side by side	-	Pass	Pass	Pass
HBM	ESD HBM	+/- 500V, 1000V	1/3/0	1/3/0	1/3/0
HTOL	C1 Life Test	150C 500 Hrs	1/45/0	1/45/0	1/45/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass	Pass	Pass

- QBS: Qual By Similarity

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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